

Finishing Up

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Timeline

- 04/23: IHP expected to update DRC (stay tuned...)
- 04/26: Pull request (preliminary files)
- 04/29: Team updates: 2, 5, 6
- 05/01: Team updates: 1, 3, 4
- 05/03: Pull request (“final” files)
- 05/22: GDS deadline

Pull Request Contents

EE628/5_Design/4_Layout/Team X

TeamX.oas → Top level layout, contains all layout cells

TeamX.spice → Top level spice netlist

TeamX.sym → Top level symbol

TeamX.readme → Pin list + any notes you want to convey

TeamX_logo.oas → In case you want to include a logo

Please submit preliminary versions of all these files by 4/26

TeamX.readme Example

TeamX pin list:

Name	Type	Purpose

vin	input	Analog input of ADC
dout	output	Digital output of ADC
res	input	Digital rese signal (active high)
avdd	supply	Analog supply voltage
...		

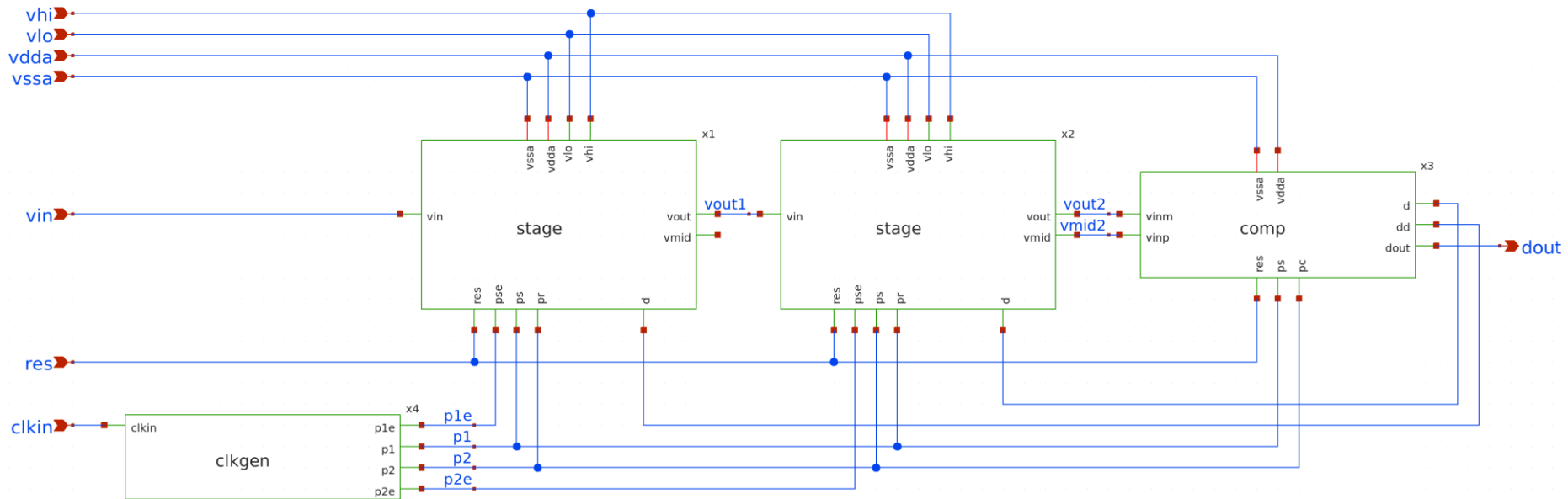
Current status:

These are the final files

Block Schematic

- Create both netlist and symbol form this schematic
 - Make sure there are no ideal spice elements!

p1: Stage 1 samples, stage 2 redistributes, comparator samples, dd toggles (used by stage 1 during p2)
p2: Stage 2 samples, stage 1 redistributes, comparator decides, d toggles (used by stage 2 during p1)



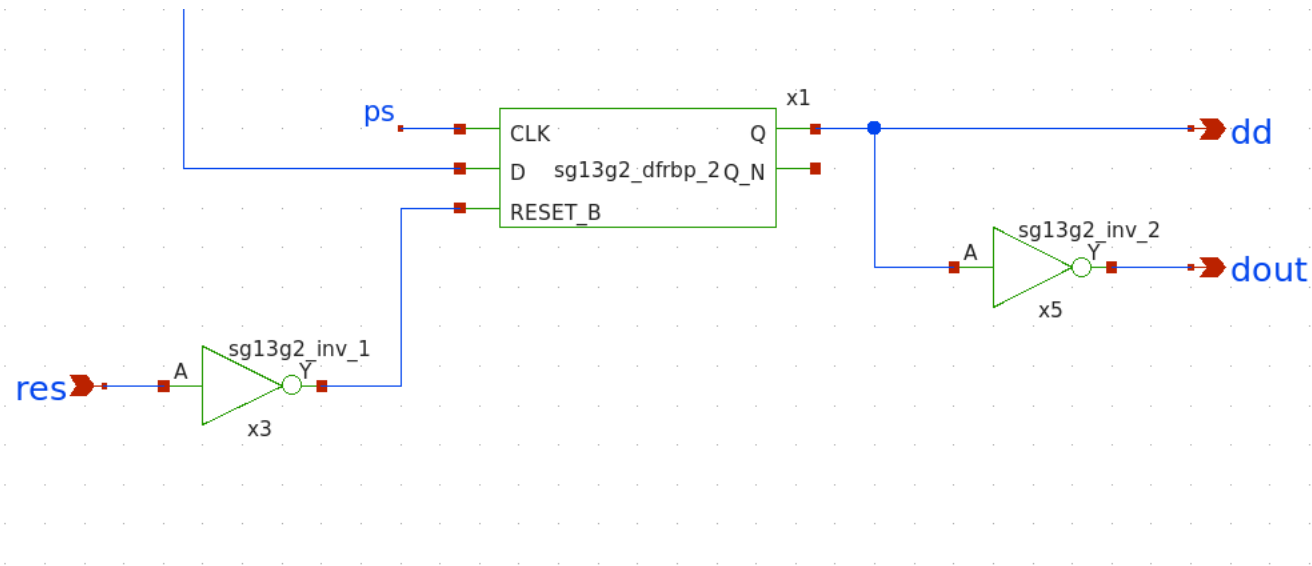
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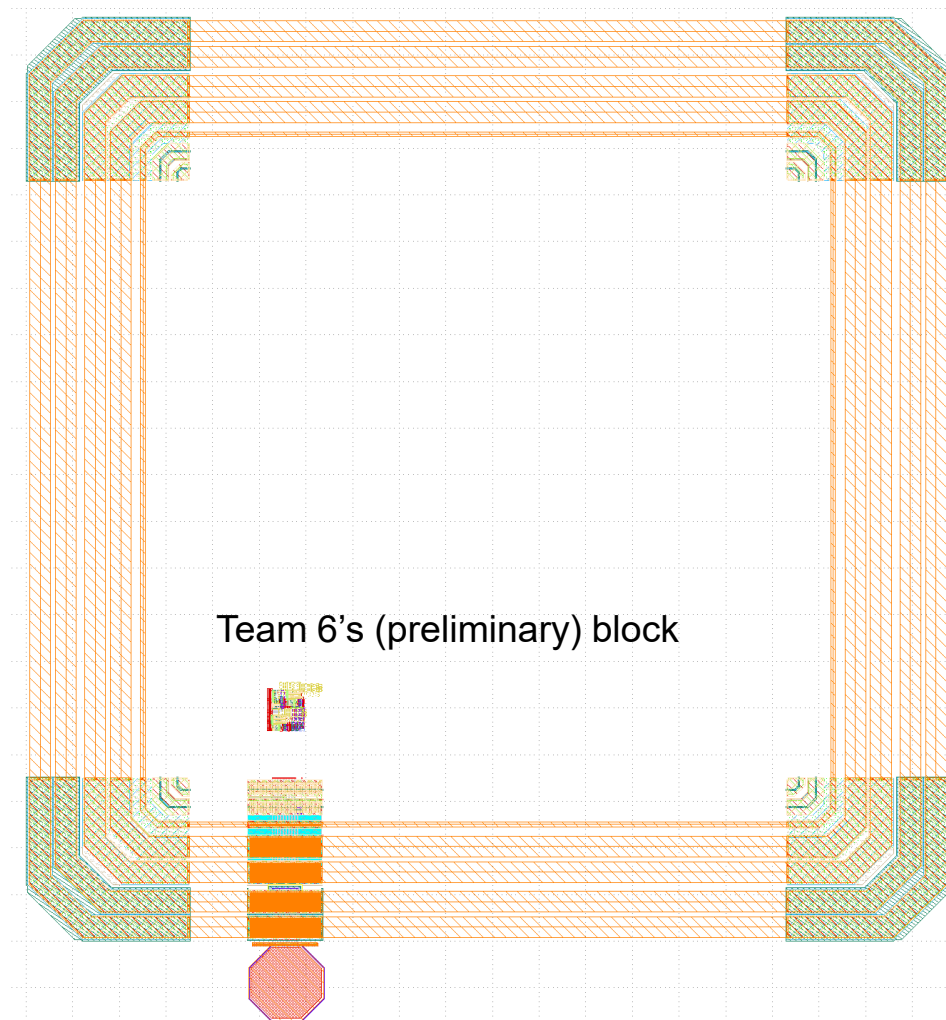
x33.

/foss/designs/EE628/5_Design/3_Real_circuits/IDSM2.sch

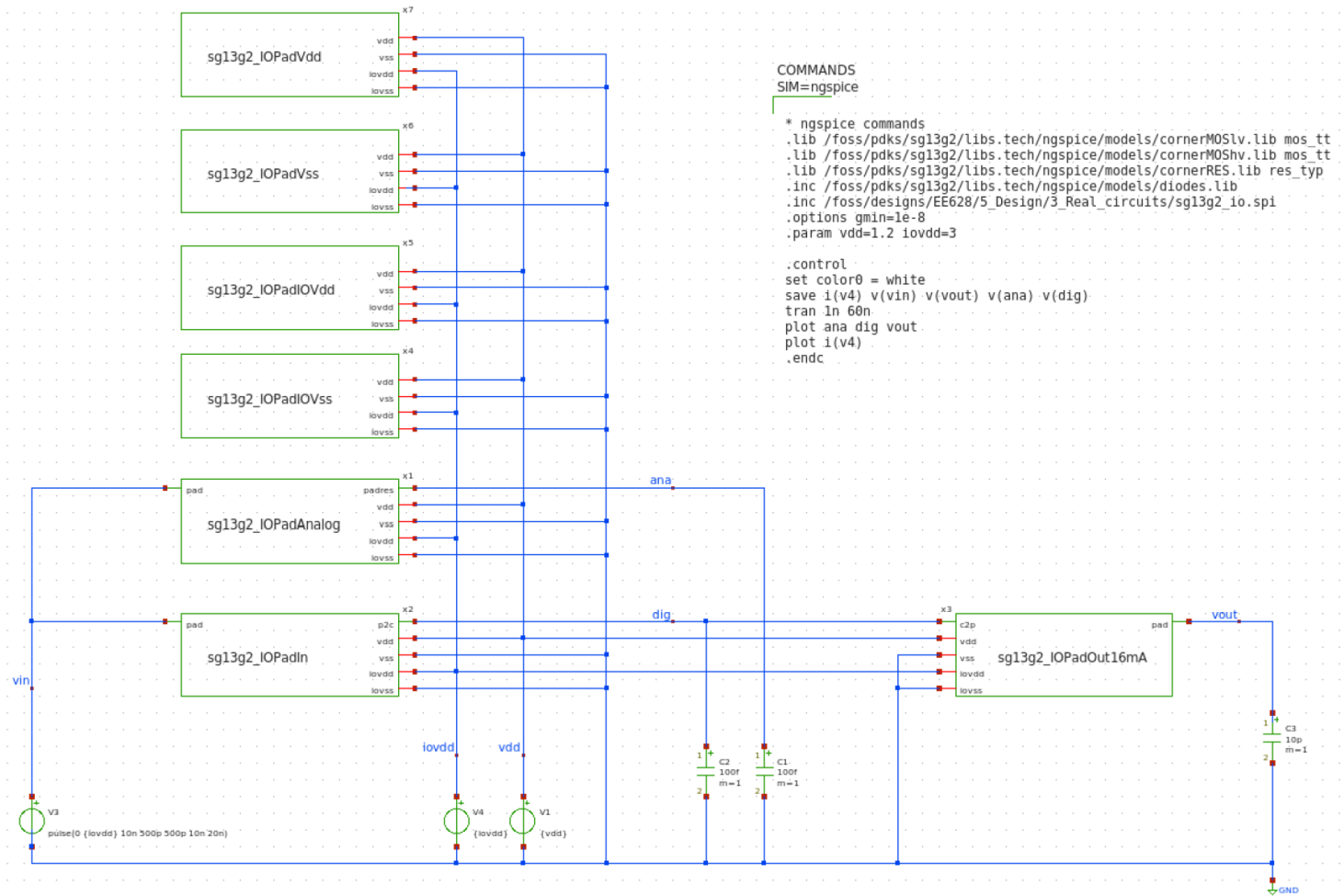
Recommended Output Signal (dout)



Preview of Chip Layout



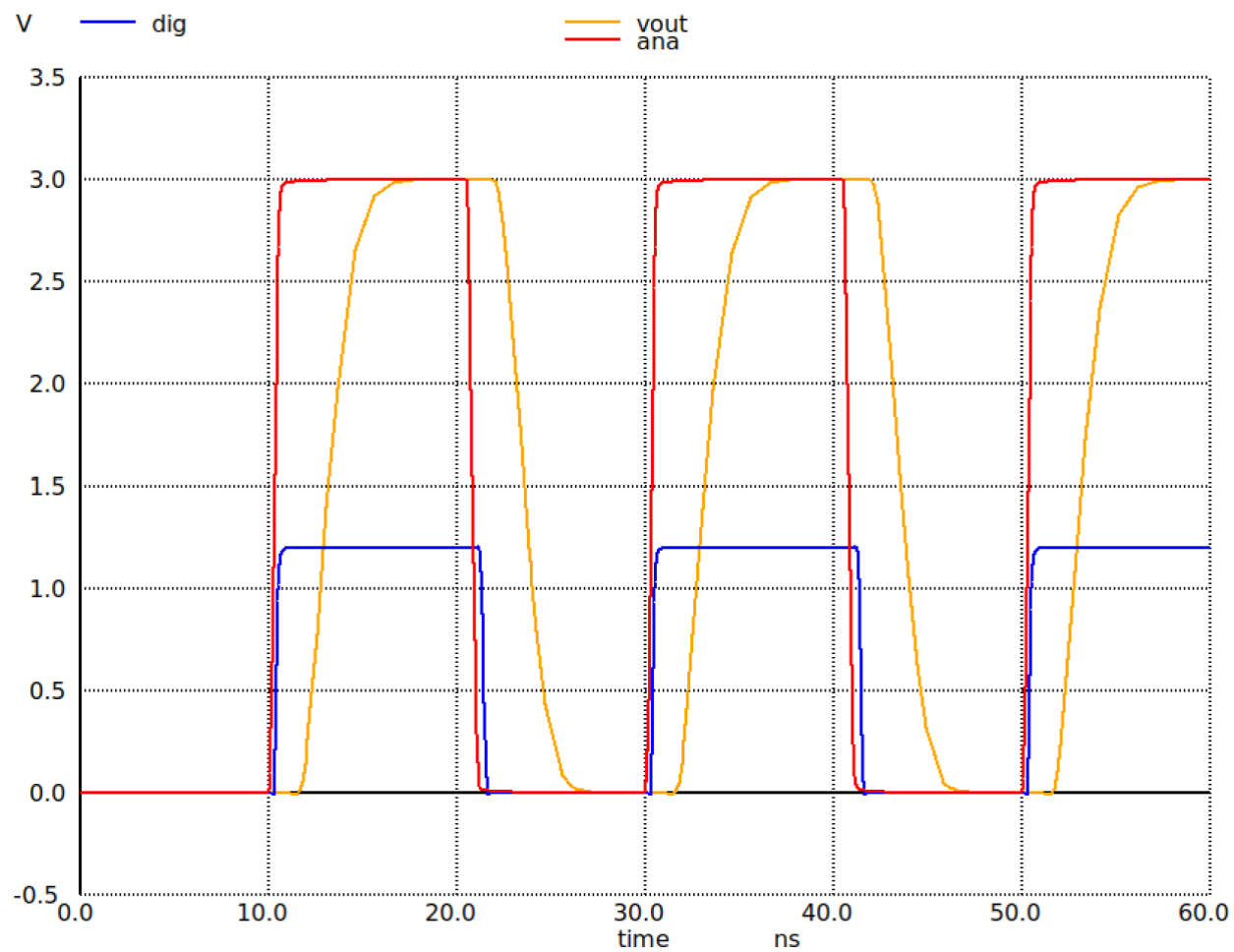
IO Cell Test



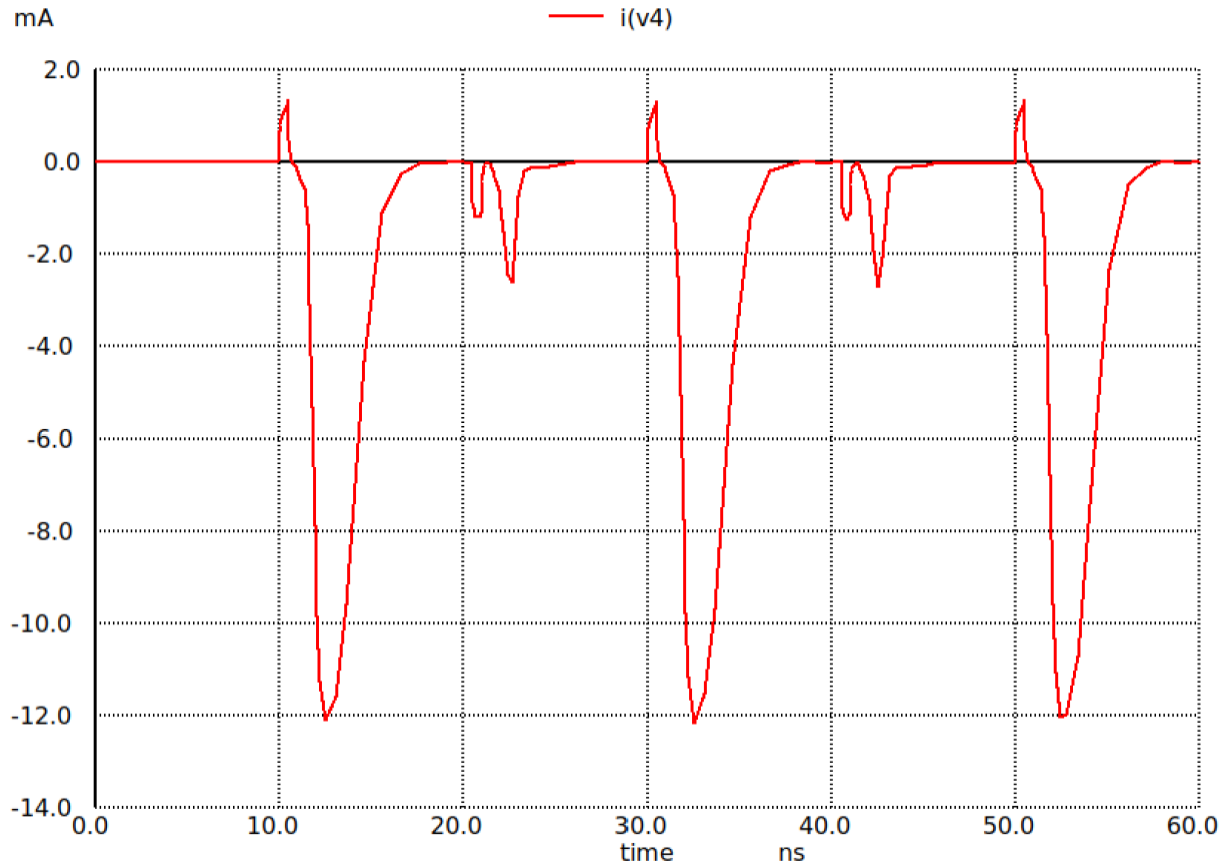
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tb_sg13g2_io.sch

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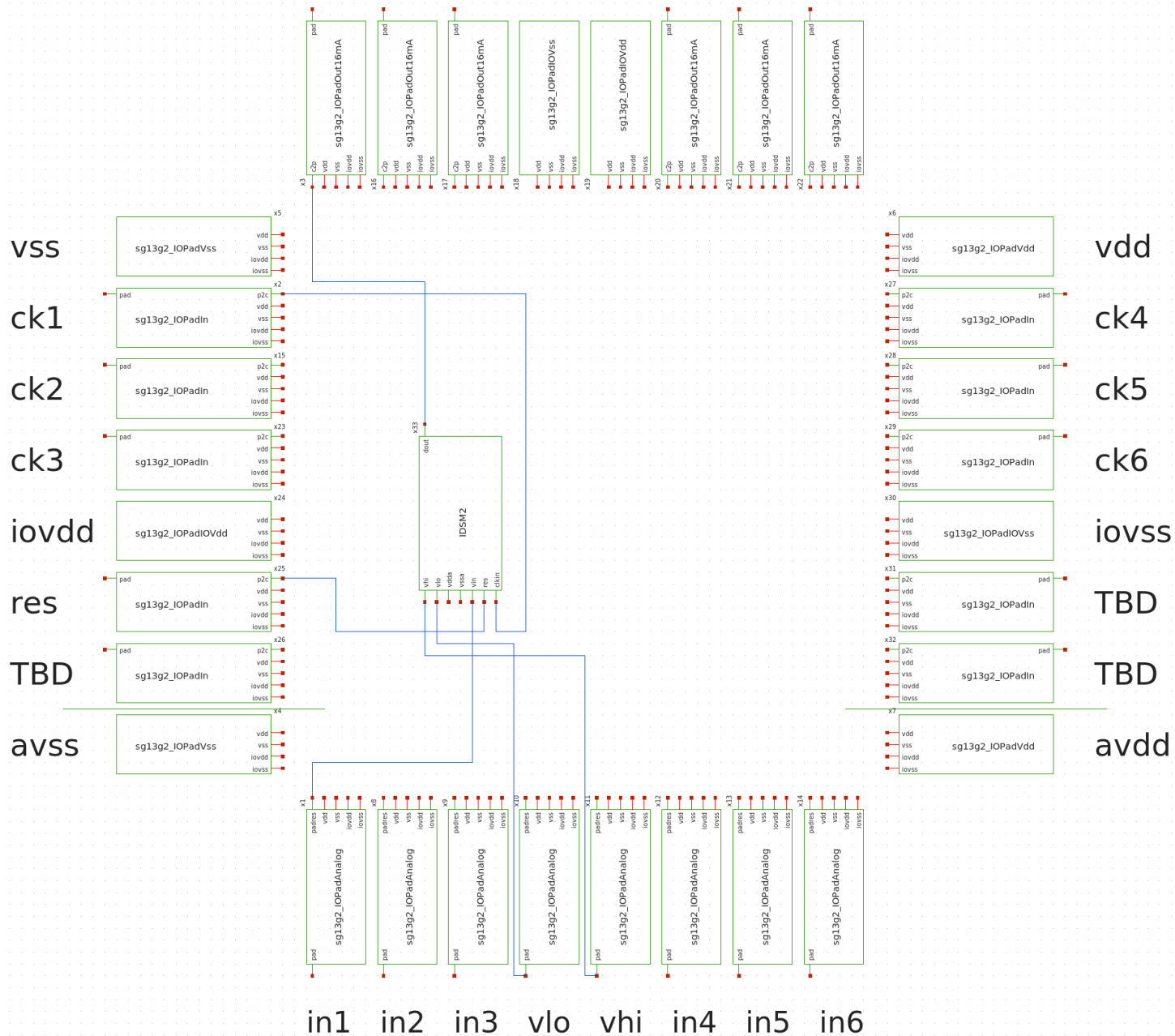
Voltage Waveforms



Digital Drive Current ($V_{DDIO} = 3V$)



out1 out2 out3 iovss iovdd out4 out5 out6



Possible Outline for Next Week's Presentations

- What is your status?
 - What have you done since the last presentation?
 - What remains to be done?
 - What problems are you facing?

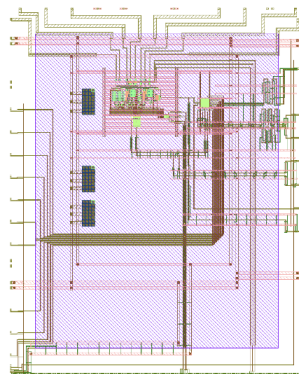
- What does your final block look like?
 - Top level schematic, pins, layout

- What have you done to check that your schematic and layout are correct?
 - Which simulations, corners?
 - How did you ensure that your layout has all the required connections?
 - In absence of LVS...

Guidelines for a Full Design Review Presentation

- Design overview
 - Walk through the system block diagram, give a big picture overview of the full system, clearly explain what is the input and what is the output
 - Show the datapath/circuit diagram of each sub-block, explain how it works
 - Talk about design decisions you made and the rationale behind them, explain the tradeoffs
- Verification of each sub-block and the entire system
 - Spice simulations, which tests did you perform?
 - How did you generate the stimuli?
 - What portions of the design are untested and what is your plan for testing them?
- Initial results
 - Estimate all design specific metrics you care about from spice simulation.
 - How do these compare with your initial specification?
 - If any devices other than MOSFETs are used, provide simulation plots showing extracted characteristics and describe the test setup.
- Integration
 - What is the approximate area of the entire circuit
 - Provide details regarding metals used for signal routing, power routing, layout methodology adopted for devices other than MOSFETs (Capacitor, Resistor, etc.)
 - I/O pin details: How many analog I/O pins, digital I/O pins, VDD, VSS pins are required?
- Plan for the remaining weeks
 - Particularly talk about your layout strategy
 - Provide a schedule with all milestones that you still need to complete for successful tapeout

- Design review example:
<https://priyanka-raina.github.io/ee372-spring2022/>



12-bit 10-KSPS Incremental Delta-Sigma ADC in Skywater 130 nm

Raymond Yang, Yaqing Xia

Code: [Design](#), [Caravel User Project](#), [analog](#)

Documentation: [Proposal](#), [Design Review](#), [Final Presentation](#), [Report](#)

This project is a 12-bit 10 KSPS incremental delta-sigma analog-to-digital converter (ADC) designed for sensor interface and instrumentation applications. The ADC consists of a second-order incremental modulator and three post-integrators. The total area of the ADC is 0.55 square mm, with 0.53 square mm for analog modulator and 0.02 square mm for digital filter.

Good Practice: Maintain a Checklist

Design Review Checklist (Digital)	
<p>Design Review Checklist (AMS)</p> <p>1. Design and simulation</p> <ul style="list-style-type: none"> <input type="checkbox"/> Detailed schematics and description emphasizing on the critical design parameters/modules. A summary of the circuit architecture with various design parameters is needed. <input type="checkbox"/> Realistic testbench for sensitive circuits (high speed signals/single-ended analog circuits/analog circuit that shares supply with switching elements, etc.). In this case, be careful about the supply network in the simulation (add bondwire model to VDD and GND). <input type="checkbox"/> Monte Carlo simulation for any circuit that needs precision, i.e. the reference voltage of comparator/current mirrors/resistor ratio etc. <input type="checkbox"/> Test circuits have to be verified extensively. Any buffer/amplifier needed? <p>2. Layout</p> <ul style="list-style-type: none"> <input type="checkbox"/> Use multiple VDD/GND pads (if available) to reduce the bonding parasitic. <input type="checkbox"/> Power distribution network (IR drop check), place decap/bypass cap at empty spaces to reduce ripple etc. <input type="checkbox"/> Critical signal routing has to consider the routing parasitic (parasitic capacitance/resistance). <input type="checkbox"/> Signal pad selection. If you want to measure precisely what the voltage/current is, you need a plain metal pad without any I/O circuits in it, and you will also need to be responsible for the ESD of it. Use analog_io if your signal speed is higher than 50 MHz or >3.3V or negative voltage. <p>3. Testing and demonstration</p> <ul style="list-style-type: none"> <input type="checkbox"/> Back-up plans for critical test circuits/signals. For example, leave the option of being able to force an external signal into the chip if some block didn't work (usually a clock signal/reference/bias etc.). <p>4. System integration</p> <ul style="list-style-type: none"> <input type="checkbox"/> All the current bias signals for submodules should be locally re-generated with one current source unless otherwise justified. <input type="checkbox"/> To avoid power distribution network oscillation, use current sources with diode-connected transistors and bypass capacitors to provide low impedance nodes for bias lines. <input type="checkbox"/> The harness provides around [0:127] independent IO controls through the on-chip Logic Analyzer. If you have more control bits than this, build shift registers to accommodate the extras. <input type="checkbox"/> DRC clean <input type="checkbox"/> LVS clean at the system level 	<p>diagram of the circuit architecture with various design</p> <p>all modules and the top level design</p> <p>passing</p> <p>test on design top passing</p> <p>test on design top passing for a stream of inputs</p> <p>ting all state (all registers and memories) via wishbone</p> <p>on caravel passing</p> <p>test exercised via wishbone only through software running</p> <p>test exercised through software running on caravel and</p> <p>digital-flow)</p> <p>positive slack</p> <p>positive slack with some margin</p> <p>IC has no violations</p> <p>connectivity has no violations</p> <p>is in all corners (best, typical, worst) in PrimeTime (with ts)</p> <p>in all corners (best, typical, worst) in PrimeTime (with cs). Must have positive slack.</p> <p>ns</p> <p>all SRAMs, DFFRAMs are connected to power and</p> <p>DS</p> <p>First run without SDF annotation then run with SDF</p> <p>ation test on design top passing</p> <p>nd power targets</p> <p>generation with openlane</p>

<https://docs.google.com/document/d/14fVJJB9oHs8LzoYUo322H58PTyj044MYgDIjb1f664o/edit>



<https://www.youtube.com/watch?v=aBDJQ9NYTEU>